



SMD Soldering Recommendations

Rev. 01

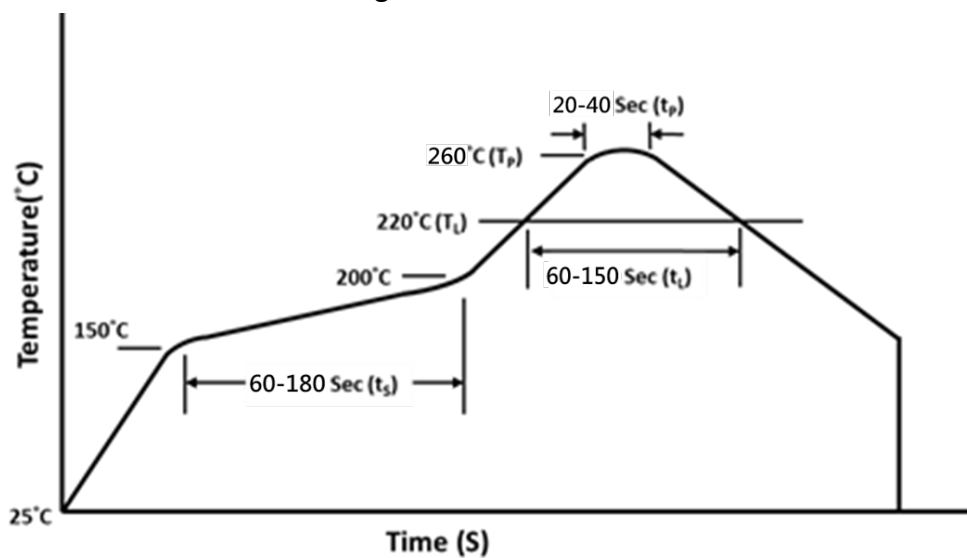
- 1. SMD products are qualified for reflow soldering. The approval for other soldering methods is product-specific. If a soldering method different from the qualified one is required, the following remarks should be considered:**
 - 1.1 The maximum temperature of the component body and leads must not exceed the maximum temperature allowed for the qualified soldering method.
 - 1.2 The maximum allowed time at high temperatures must not exceed the maximum time allowed for the qualified soldering method.
 - 1.3 If increased heat is applied to the leads (e.g. during iron soldering), the maximum temperatures in the package and of the package body must not exceed the maximum temperatures allowed during the qualified soldering method.
 - 1.4 In order to prevent damage to the component, mechanical or thermo-mechanical overstress during manual handling and soldering must be avoided (especially contact between the soldering iron or hot-air gun and the component package).
 - 1.5 Wave soldering of packages is not recommended since they are qualified only for reflow temperature profiles.

2. Recommended Reflow Soldering Profile

2.1 Classification Reflow Parameter

Parameter	Value	
Preheat ramp up rate	1~3	°C/sec
Soaking Temperature	150~200	°C
Soaking Time	60~180	sec
Peak Temperature	260	°C
Cool down rate	1~6	°C/sec
Number of allowed reflow cycles	3	

2.2 Classification Reflow Soldering Profile



Note

- Applicable for Pb-free solder paste under convection reflow.
- The reflow profile herein is for reference only. Users are advised to optimize their own parameters to get proper reflow outcome.

Revision History

Revision	Date	Description of Change
00	2020-12-23	First Release
01	2022-04-14	2. Recommended Reflow Soldering Profile revised